

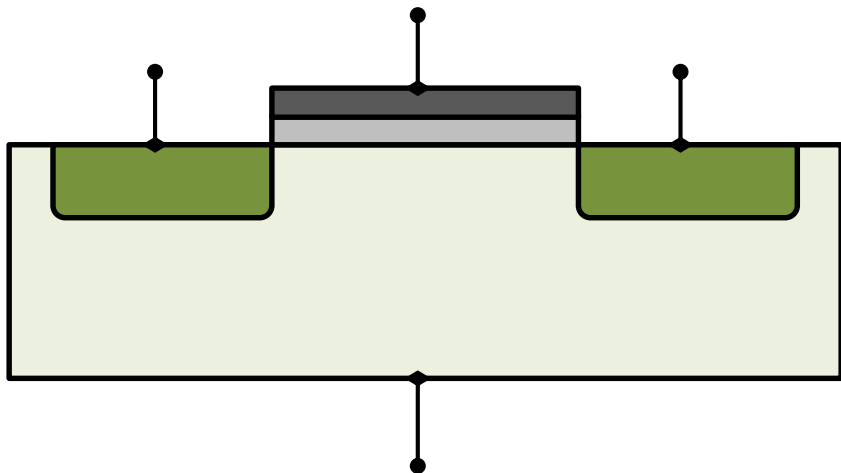
MOSFET → Chapter 5

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- MOS – Metal Oxide Semiconductor
- FET – Field-Effect Transistor
- 4 terminal device

Advantages:

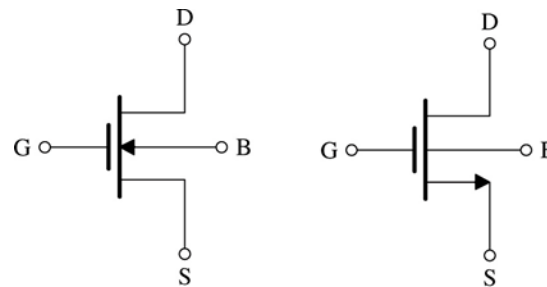
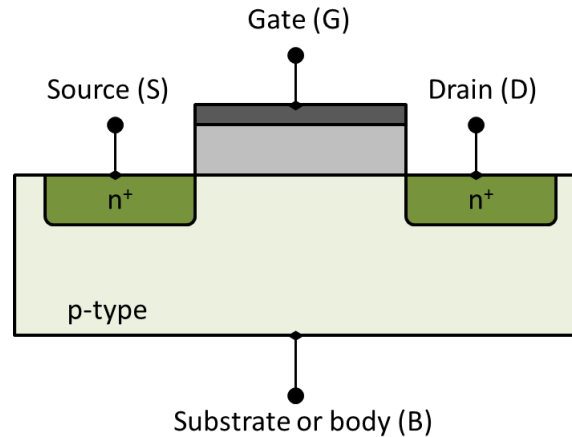
- Small area; comparatively
- Less power
- Relatively simple manufacturing process



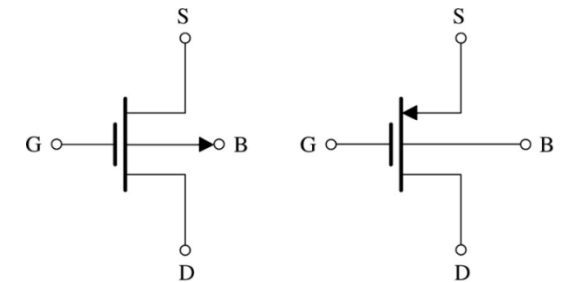
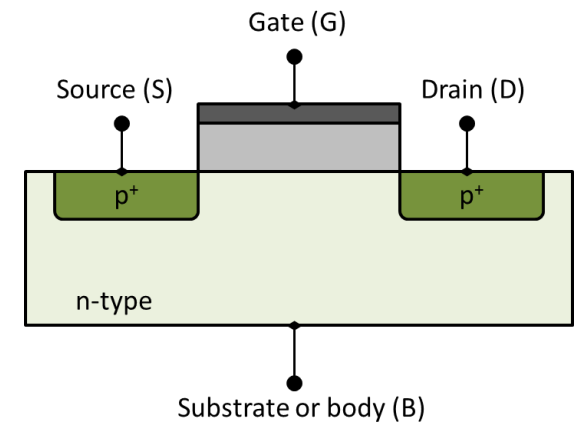
Cross Section Diagram

* If the bulk terminal is omitted, it is presumed is connected to the source

• nMOS Transistor



• pMOS Transistor



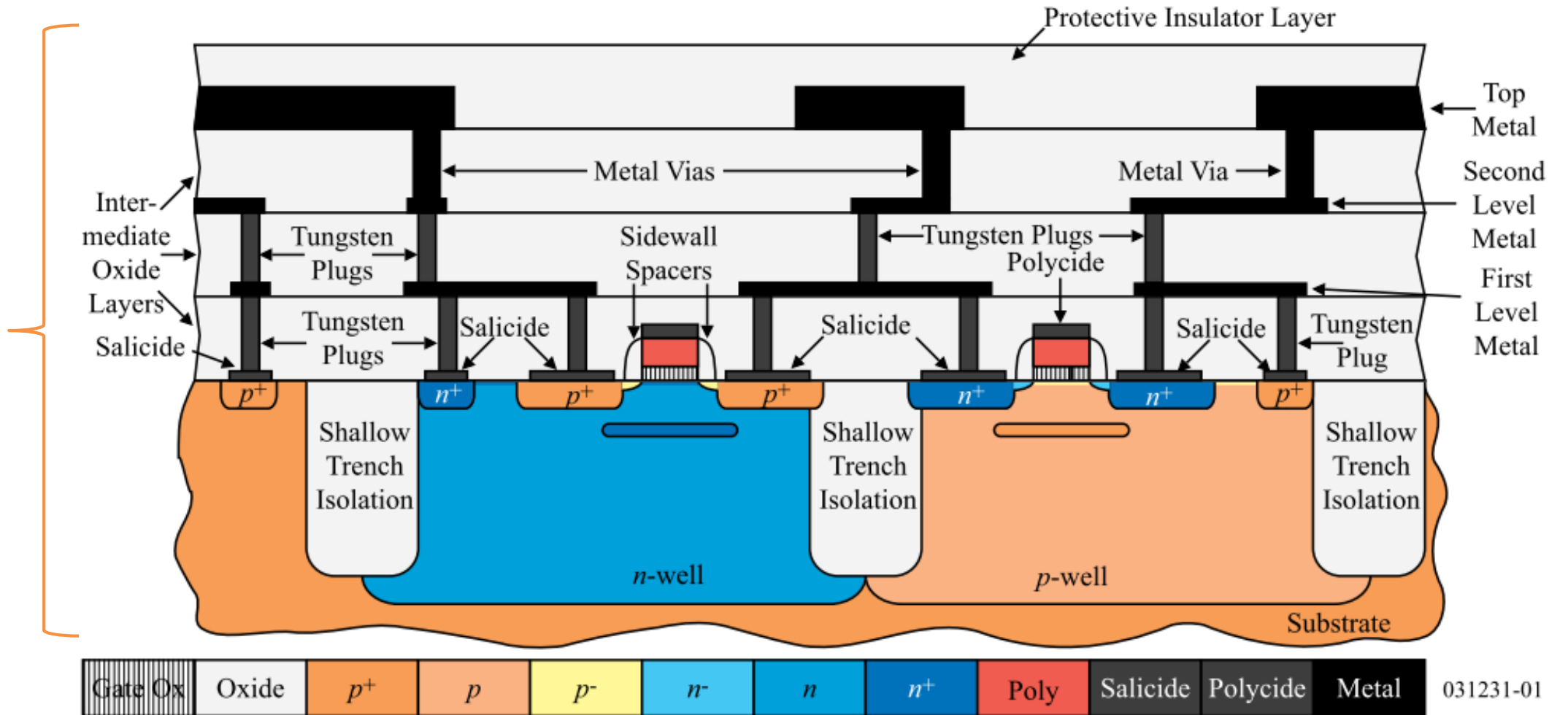
Symbol

Modern CMOS Technology

Twin-Well Process

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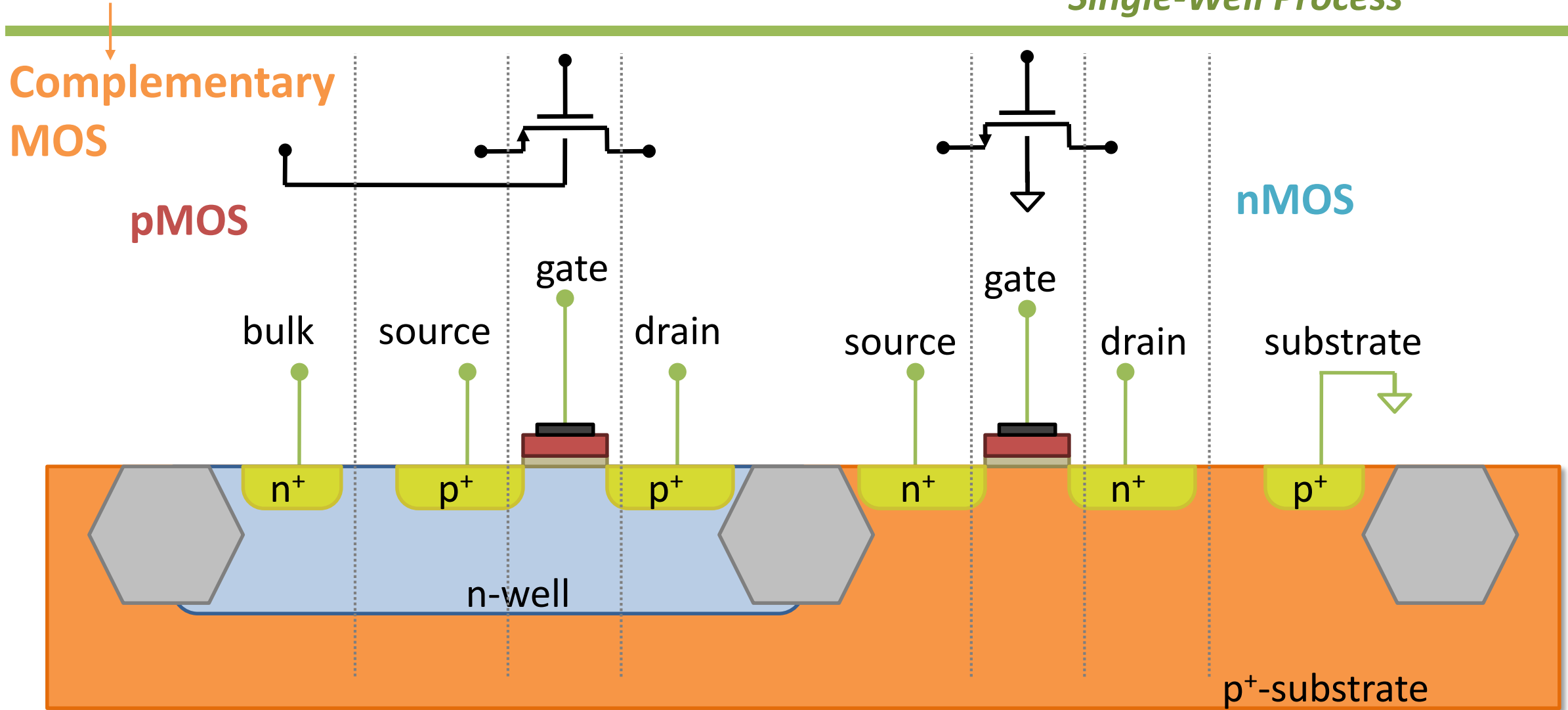
IC - Cross-Section



CMOS Transistors

Single-Well Process

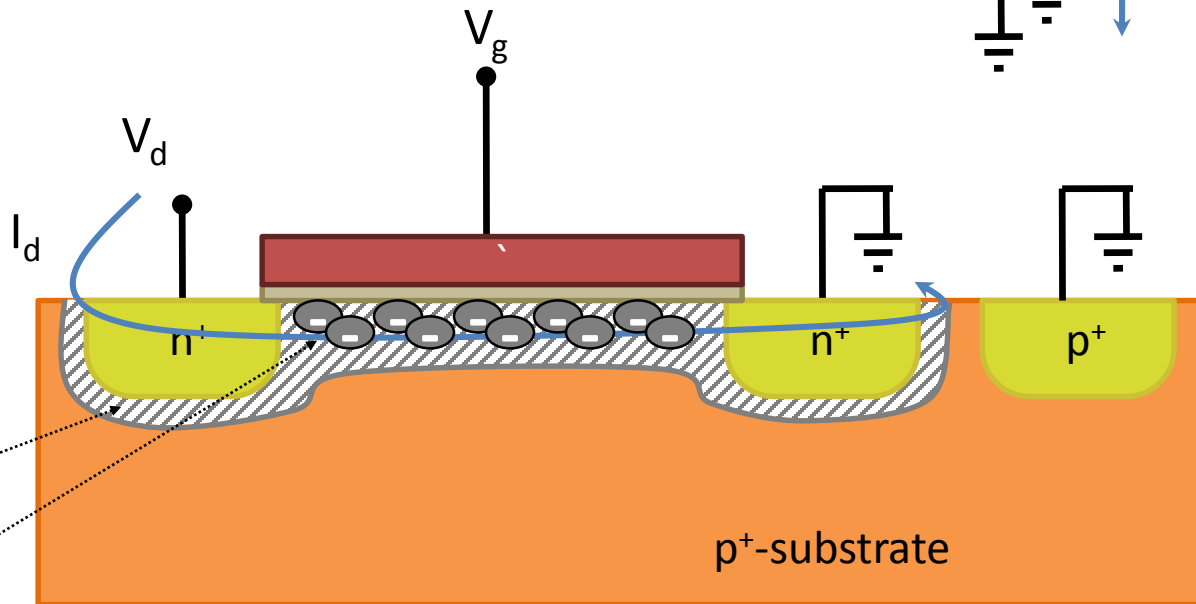
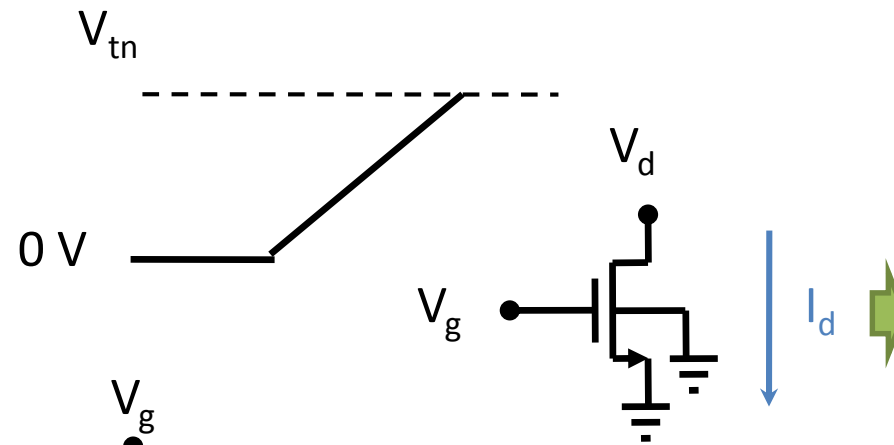
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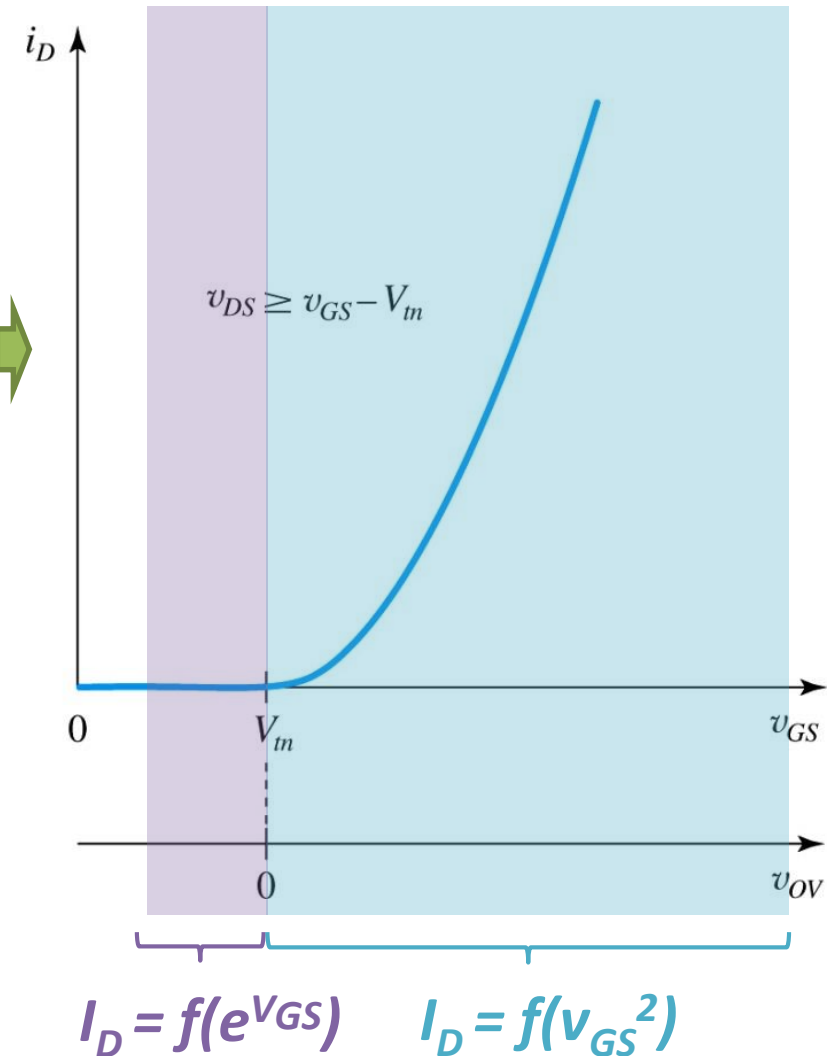
Operation Regions

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- 1) Cut-Off
- 2) Strong - Inversion
- 3) Weak - Inversion

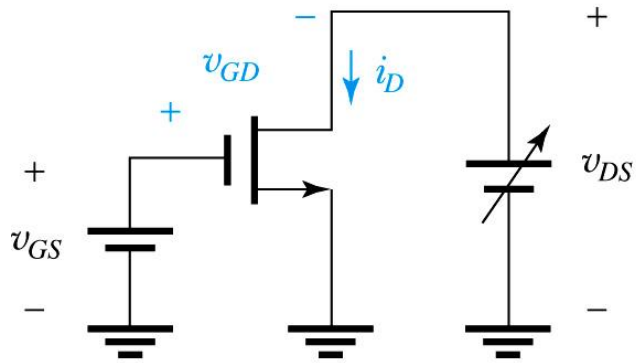


depletion layer
inversion layer



nMOS Strong Inversion → Saturation

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- $V_{GS} > V_{tn}$
- $V_{DS} > V_{GS} - V_{tn}$
- $i_G = 0$

Over-drive Voltage $V_{ov} = V_{GS} - V_{tn}$

$$i_D \approx f(V_{GS}^2)$$

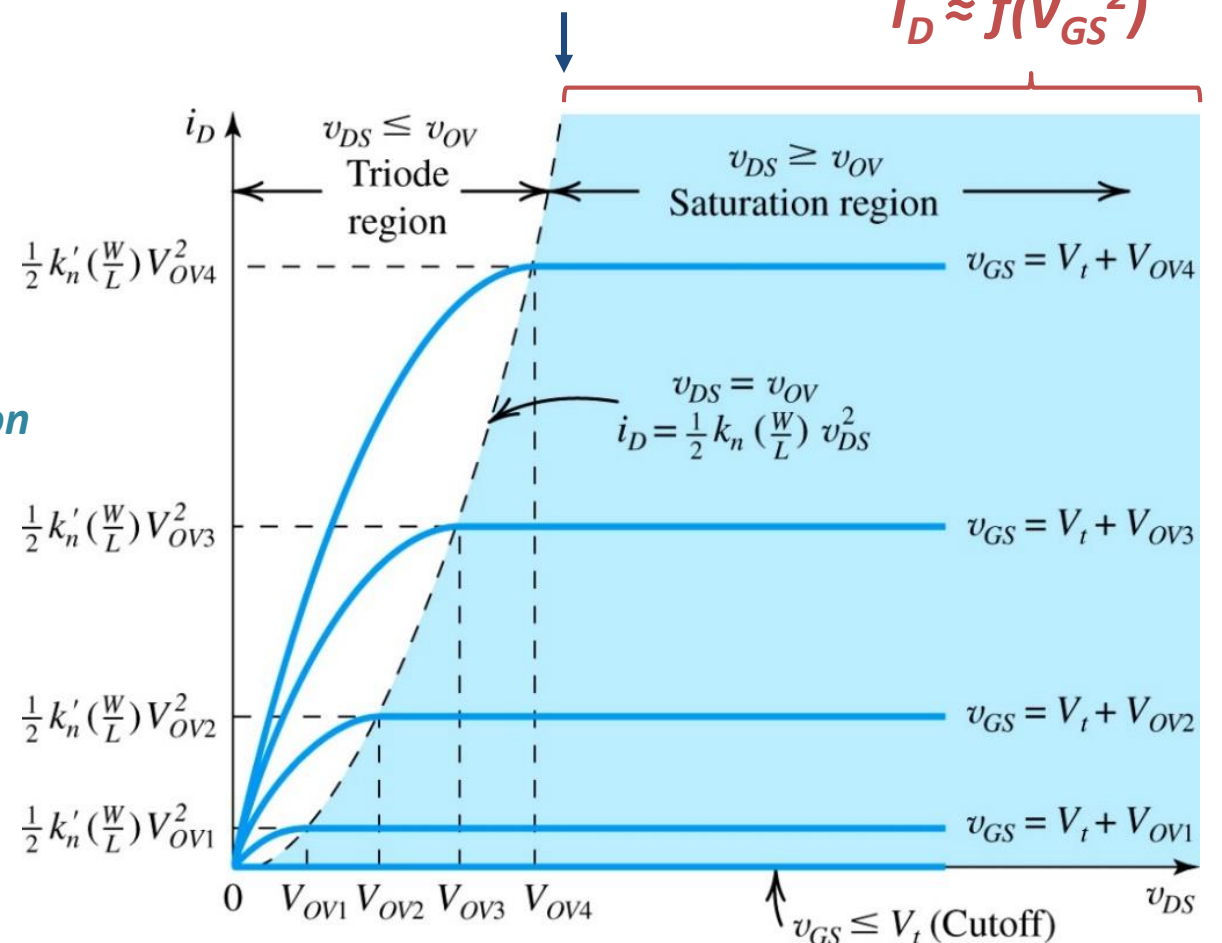
Channel Length Modulation
Parameter [1/V]

$$I_D = \frac{1}{2} \underbrace{k_n'}_{K_n} \frac{W}{L} (V_{GS} - V_{tn})^2 (1 + \lambda V_{DS})$$

$$\approx \frac{1}{2} k_n' \frac{W}{L} (V_{GS} - V_{tn})^2$$

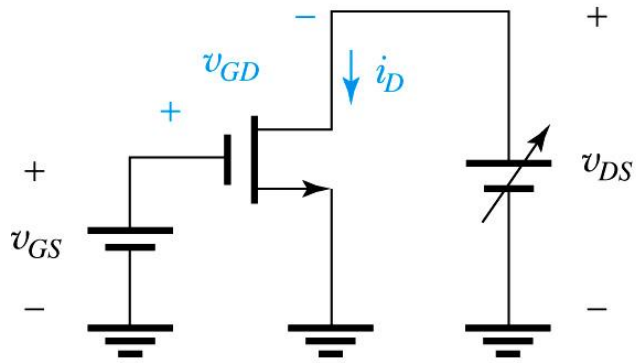
nMOS Transconductance Parameter [A/V²]

$$k_n' = \mu_n C_{ox}$$



nMOS Strong Inversion → Ohmic

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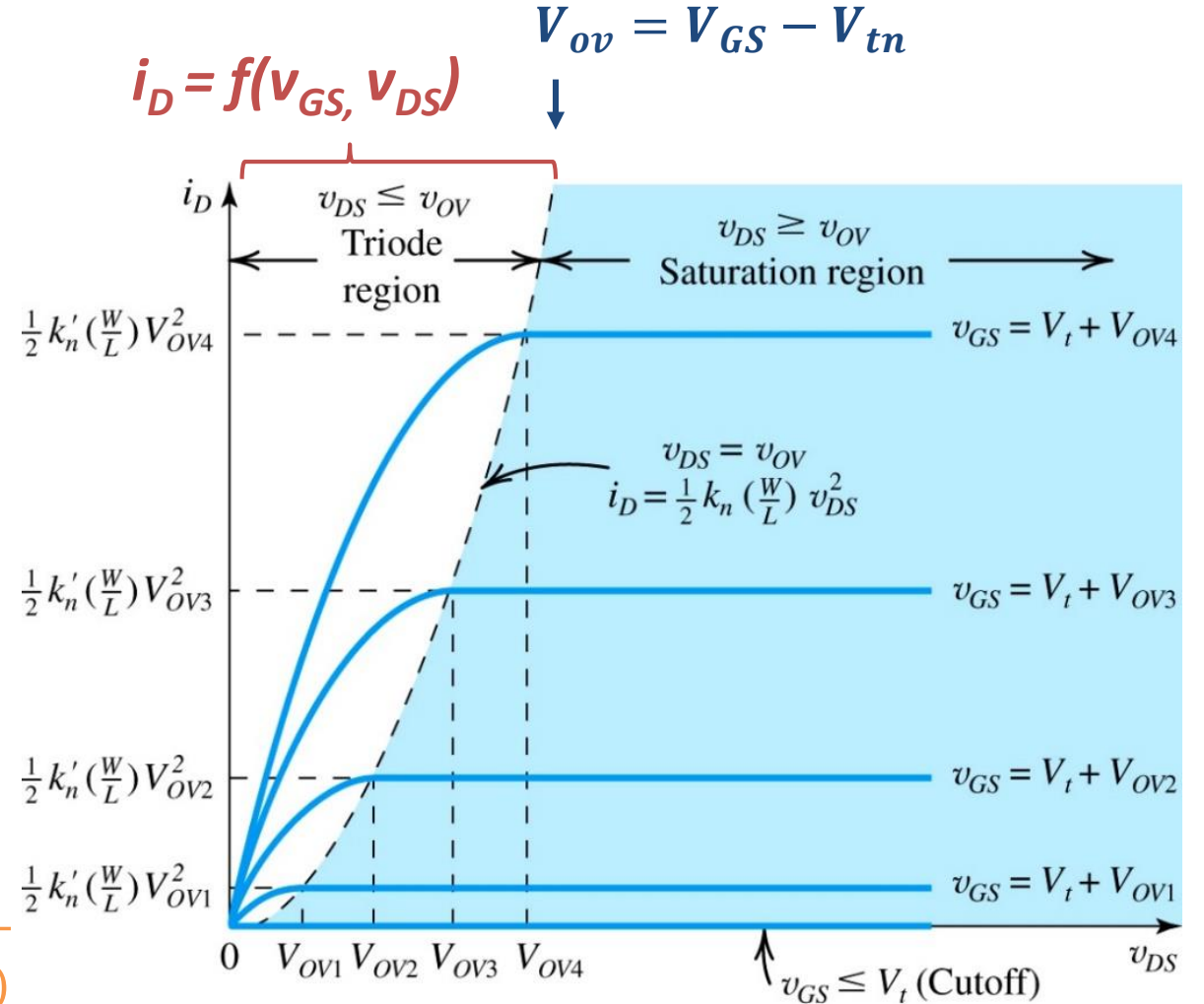


- $V_{GS} > V_{tn}$
- $V_{DS} < V_{GS} - V_{tn}$
- $i_G = 0$

$$I_D = k_n' \frac{W}{L} \left[(V_{GS} - V_{tn})(V_{DS}) - \frac{1}{2} V_{DS}^2 \right]$$

$$\approx k_n' \frac{W}{L} (V_{GS} - V_{tn}) \cdot V_{DS}$$

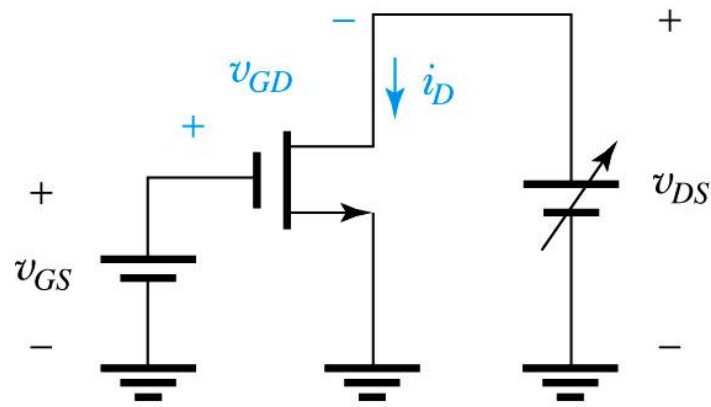
$$r_{ds} = \frac{1}{k_n' \frac{W}{L} (V_{GS} - V_{tn})}$$



Overdrive Voltage

Additional voltage required at V_{GS} to be able to conduct a given current I_D

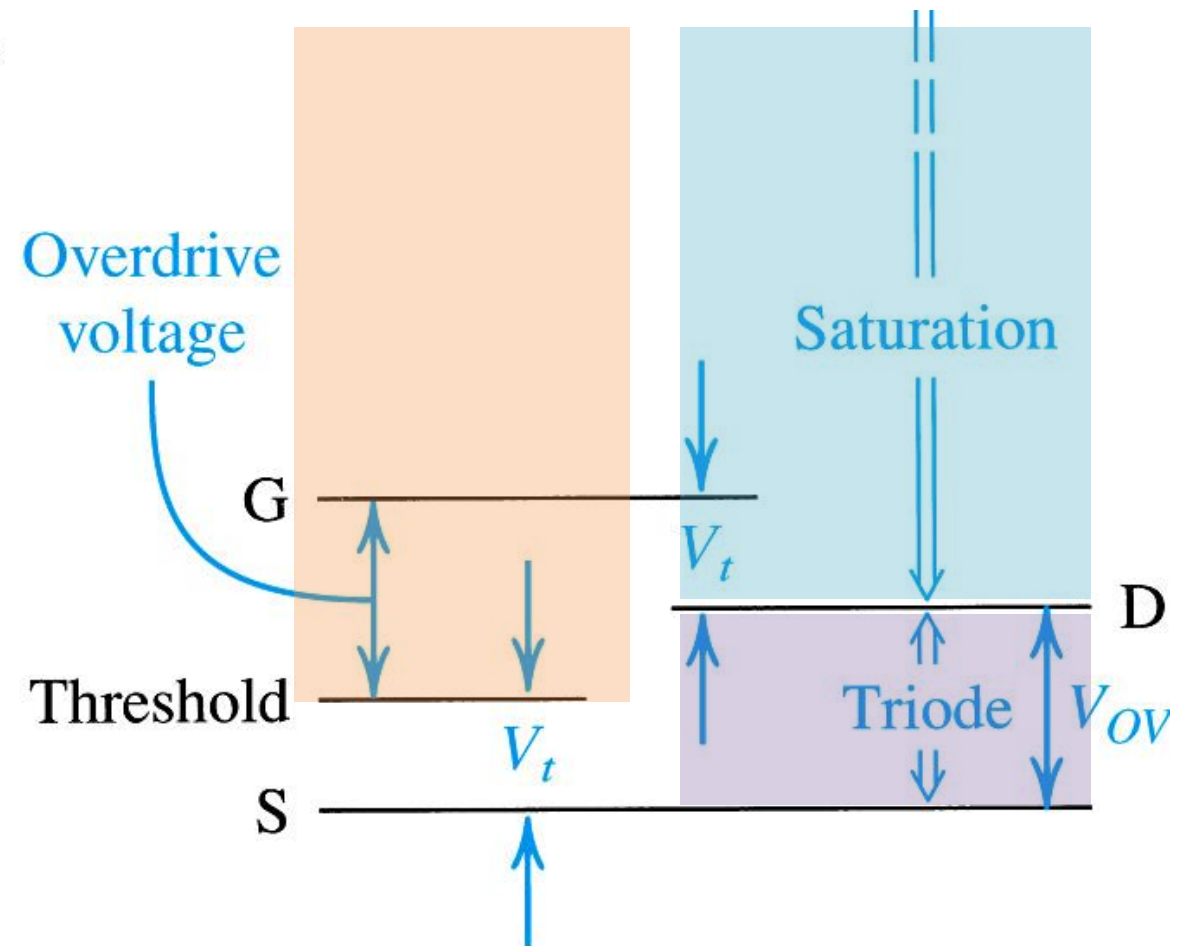
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$V_{GS} > V_{tn} \rightarrow$ **Strong Inversion**

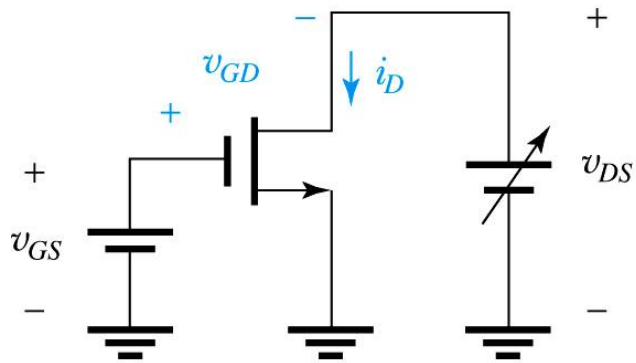
- $V_{DS} > V_{ov} \rightarrow$ **Saturation**
- $V_{DS} < V_{ov} \rightarrow$ **Ohmic**

$$V_{ov} = V_{GS} - V_{tn} = \sqrt{\frac{2I_D}{K_n}}$$



nMOS Weak Inversion → Saturation

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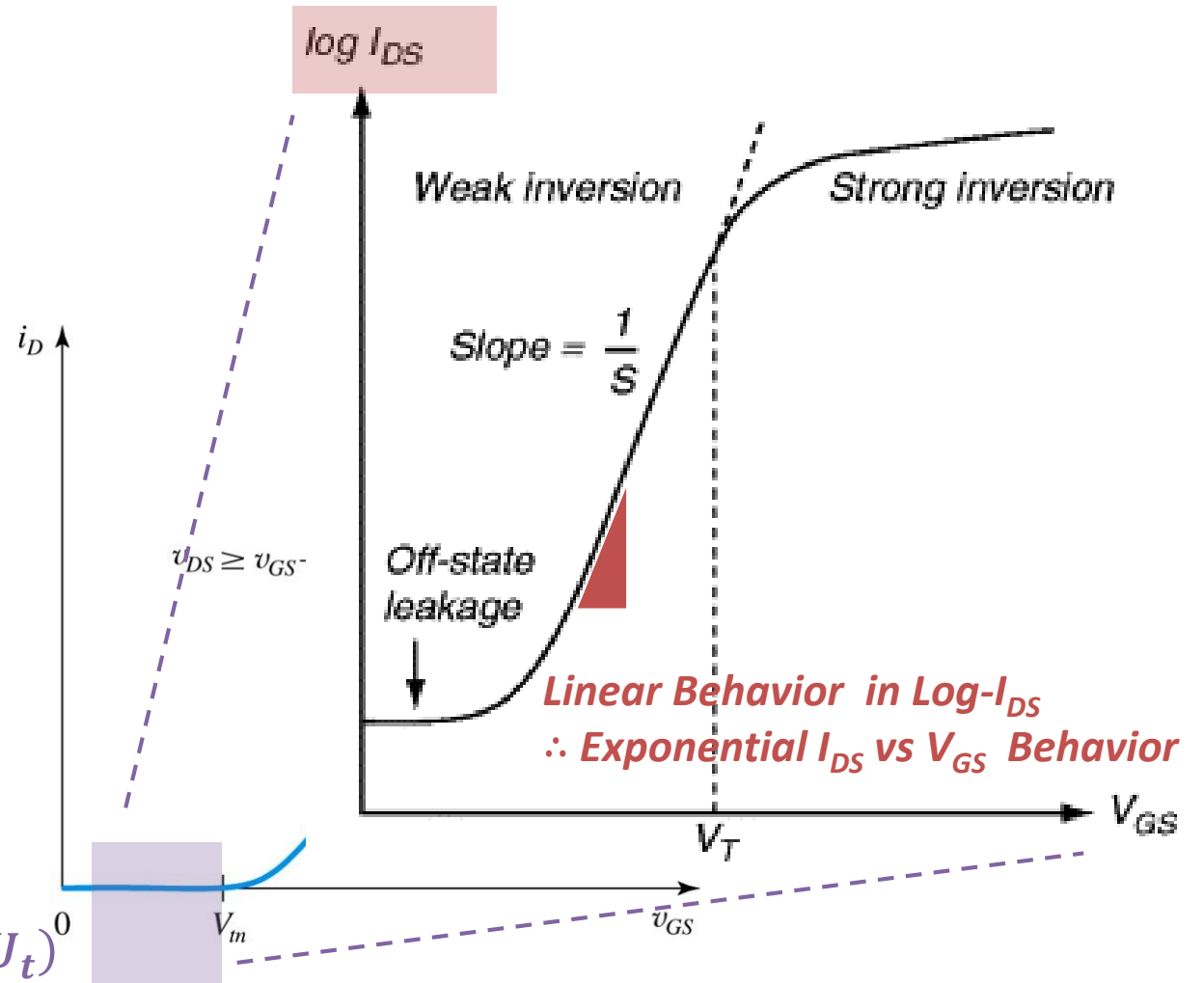


- $V_{GS} < V_{tn}$
- $V_{DS} > 0.1 \text{ V}$

$$I_D = I_0 e^{\frac{V_{GS} - V_{tn}}{n \cdot U_t}}$$

Slope Factor
 $n = [1 : 2]$

Thermal Voltage [V]
 $U_t \propto T$
 $U_t \approx 25 \text{ mV} @ 25^\circ \text{C}$



$$(V_{tn} - 5 \cdot U_t) < V_{GS} < (V_{tn} - 2 \cdot U_t)$$

nMOS Large Signal Model

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- Strong Inversion – Ohmic

$$I_D = \mu C_{ox} \frac{W}{L} \left[(V_{GS} - V_{th}) V_{DS} - \frac{V_{DS}^2}{2} \right]$$

Condition

$$\begin{aligned} V_{GS} &> V_{th} \\ V_{DS} &< V_{OV} \end{aligned}$$

- Strong Inversion - Saturation

$$I_D = \frac{\mu C_{ox} W}{2 L} (V_{GS} - V_{th})^2 (1 + \lambda V_{DS})$$

$$\begin{aligned} V_{GS} &> V_{th} \\ V_{DS} &> V_{OV} \end{aligned}$$

- Weak Inversion - Saturation

$$I_D = I_0 \cdot e^{\frac{V_{GS} - V_{th}}{n U_T}}$$

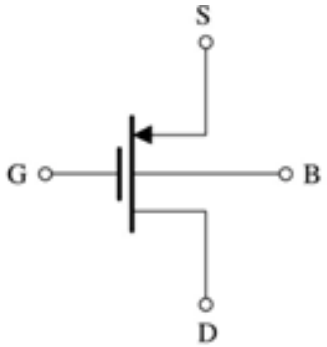
$$V_{th} - 5 \cdot U_T < V_{GS} < V_{th} - 2 \cdot U_T$$

Weak Inversion vs Strong Inversion?

Weak Inversion	Strong Inversion
Saturation current is exponential in V_{GS}	Saturation current is square law in V_{GS}
V_{DSAT} is constant at approximately 100mV	V_{DSAT} varies linearly with gate voltage
Current flows by diffusion	Current flows mainly by drift
Charge concentrations are small	Charge concentrations are large
Currents are small	Current are large
Good for ultra-low-power operation	Good for high-power operation
Power efficiency is constant with current	Power efficiency is lower
High noise and offset	Low noise and offset
Can work on low power supply voltage	Needs higher power supply voltages
Linearity is hard to achieve	Linearity is easy to achieve
Suited for slow-and-parallel architectures	Suited for fast-and-serial architectures

pMOS Large Signal Model

10/28/2019



Saturation Mode

- $v_{SG} > |v_{tp}|$
- $v_{SD} > v_{SG} - |v_{tp}|$
- $i_G = 0$

$$I_D = \frac{1}{2} k_p' \frac{W}{L} (V_{SG} - |V_{tp}|)^2 (1 + \lambda V_{SD})$$

$$\approx \frac{1}{2} k_p' \frac{W}{L} (V_{SG} - |V_{tp}|)^2$$

$$V_{ov} = V_{SG} - |V_{tp}|$$

Ohmic Mode

- $v_{SG} > |v_{tp}|$
- $v_{SD} < v_{SG} - |v_{tp}|$
- $i_G = 0$

$$I_D = k_p' \frac{W}{L} \left[(V_{SG} - |V_{tp}|)(V_{SD}) - \frac{1}{2} V_{SD}^2 \right]$$

$$\approx k_p' \frac{W}{L} (V_{SG} - |V_{tp}|) \cdot V_{SD}$$

pMOS Transconductance Parameter [A/V²]

$$k_p' = \mu_p C_{ox}$$

MOSFET Model Parameters

$U_t = kT/q$ → thermal voltage (~25mV @ room temp.)

μ → electron/hole mobility

$\kappa_s = 1/n$ → subthreshold slope coefficient (unit-less)

$C_{ox} = \epsilon_{ox}/t_{ox}$ → gate oxide capacitance per unit area (F/cm²)

ϵ_{ox} → dielectric permittivity of SiO₂

t_{ox} → oxide thickness

$K_n = k_n' \cdot W/L$ → transconductance parameter (A/V²)

$k_n' = \mu C_{ox}$

γ → body effect coefficient (V^{1/2})

λ → channel-length modulation parameter (V⁻¹)

V_{T0} → threshold voltage at $V_{SB}=0$ (V)

V_T → threshold voltage (V)

ϕ_0 → ≈ surface potential (V)

Threshold Voltage

The required voltage to produce and inversion layer.

$$V_T = V_{T0} + \gamma(\sqrt{\phi_0 + V_{SB}} - \sqrt{\phi_0})$$

V_{T0}
 γ
 V_{SB}
 ϕ_0

body effect coefficient
surface potential

$$V_{T0} = \phi_{ms} + 2\phi_F + \frac{Q_{dep}}{C_{ox}}$$

ϕ_{ms}
 $2\phi_F$
 $\frac{Q_{dep}}{C_{ox}}$

work-function difference between the gate metal and the silicon
Fermi level

work-function difference between the gate metal and the silicon

voltage required to sustain the depletion layer

The threshold voltage is a function of V_{SB} !!!

Example 5.2

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Consider an nMOS transistor fabricated in a $0.18\mu\text{m}$ process with $L=0.18\mu\text{m}$ and $W=2\mu\text{m}$. The process technology is specified to have $C_{\text{ox}}=8.6\text{fF}/\mu\text{m}^2$, $\mu_n=450\text{cm}^2/\text{V}\cdot\text{s}$, and $V_{\text{th}}=0.5\text{V}$.

- Find V_{GS} and V_{DS} that result in the MOSFET operating at the edge of saturation with $I_{\text{D}}=100\mu\text{A}$.
- If V_{GS} is kept constant, find V_{DS} that results in $I_{\text{D}}=50\mu\text{A}$.
- To investigate the use of the MOSFET as a linear amplifier, let it be operating in saturation with $V_{\text{DS}}=0.3\text{V}$. Find the change in i_{D} resulting from v_{GS} changing from 0.7V by $+0.01\text{V}$ and by -0.01V .

Example 5.5

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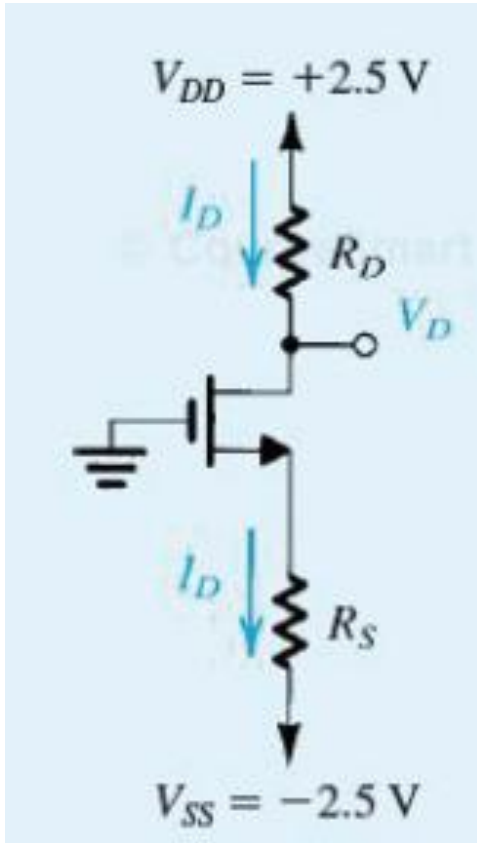
An n-channel MOSFET operating with $V_{ov}=0.5V$ exhibits a linear resistance $r_{DS}=1k\Omega$ when v_{DS} is very small.

- What is the value of the device trans-conductance parameter K_n ?
- Assuming $\lambda = 0$, what is the value of the current I_D obtained when v_{DS} is increased to 0.5V? And to 1V?
- Assuming an $\lambda = 0.1V^{-1}$, what is the value of the current I_D obtained when v_{DS} is increased to 0.5V? And to 1V?

Example 5.3

10/28/2019

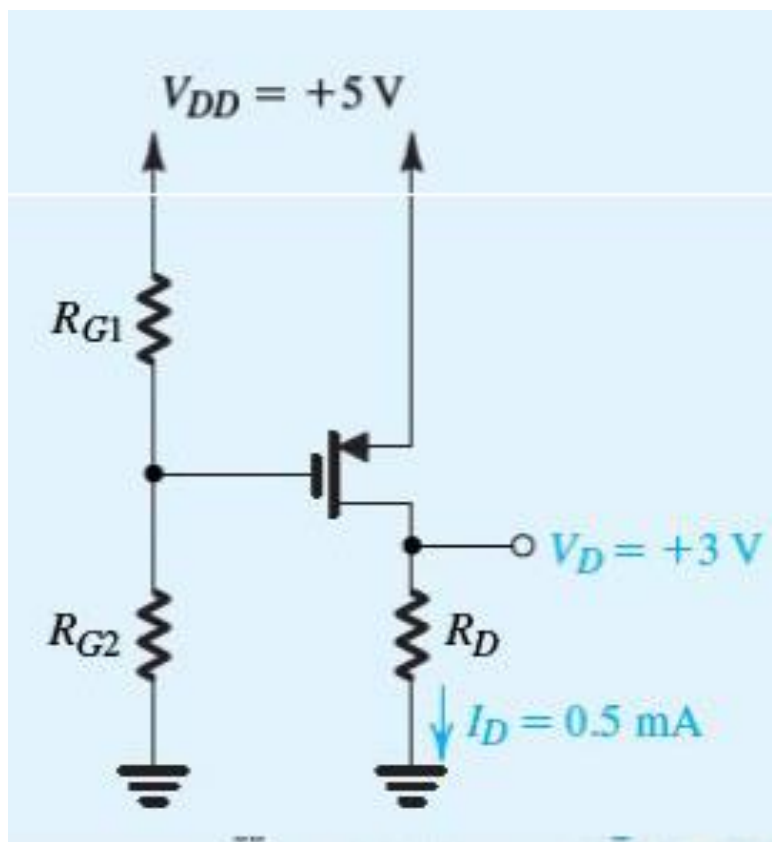
Assuming $\lambda=0$, design the circuit below, that is, determine the values of R_D and R_S , so that the transistor operates at $I_D=0.4\text{mA}$ and $V_D=0.5\text{V}$. The NMOS transistor has $V_{th}=0.7\text{V}$, $\mu_n C_{ox}=100\mu\text{A}/\text{V}^2$, and $W/L=32$.



Example 5.7

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Assuming $\lambda=0$, design the circuit below, so that the transistor operates in saturation with $I_D=0.5\text{mA}$ and $V_D=3\text{V}$. The PMOS transistor has $V_{th}=-1\text{V}$, $K_p=1\text{mA/V}^2$. What is the largest value that R_D can have while maintaining saturation-region operation?

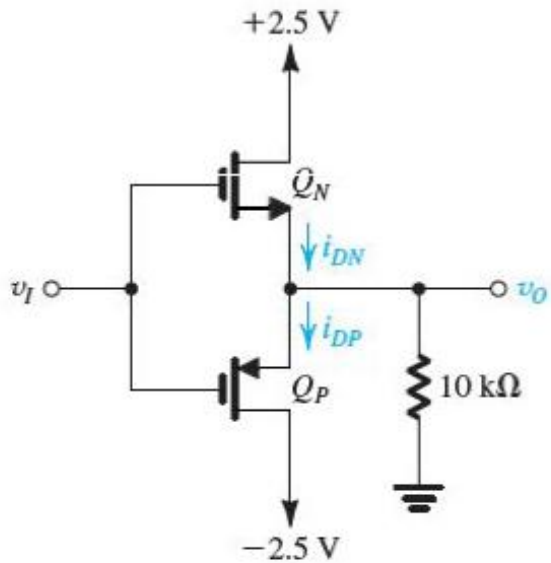


MOS Behavior → Intuitively

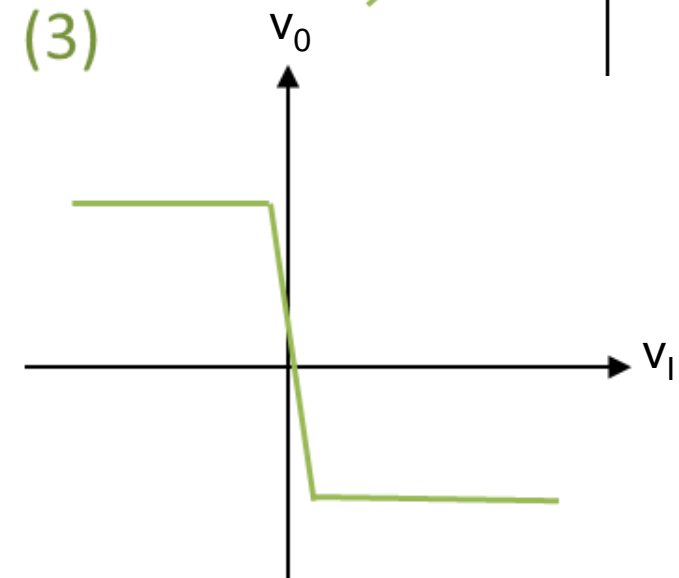
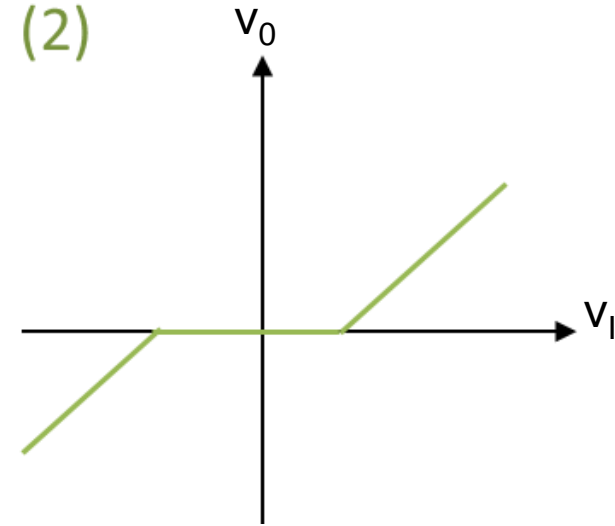
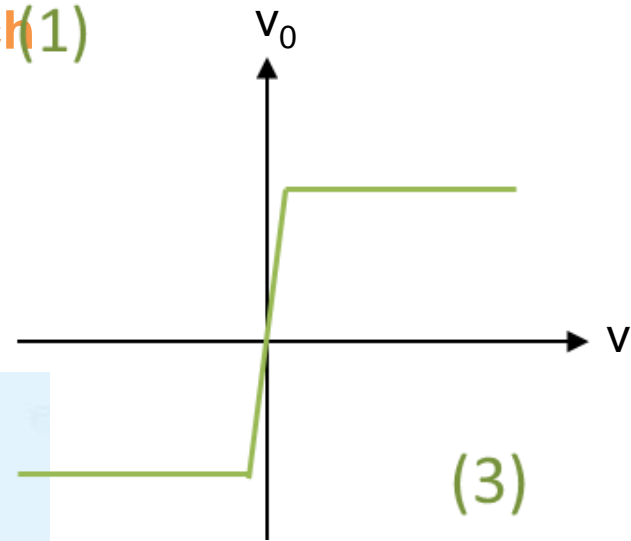
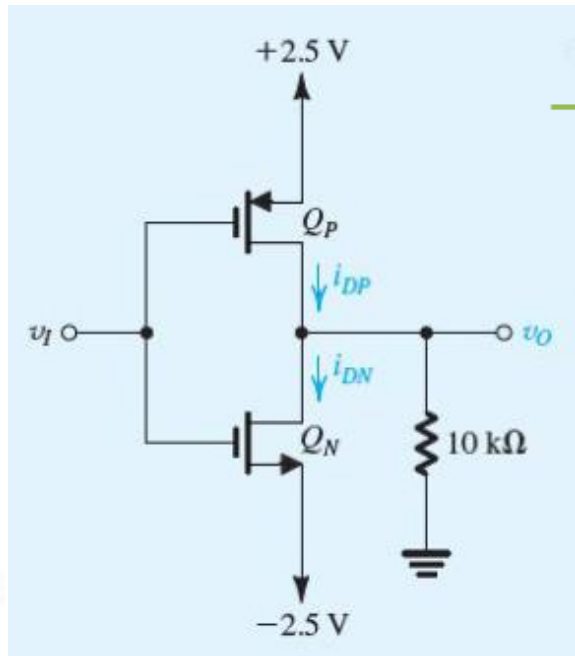
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Choose the plot that best represents each circuit behavior!

Circuit (a) _____



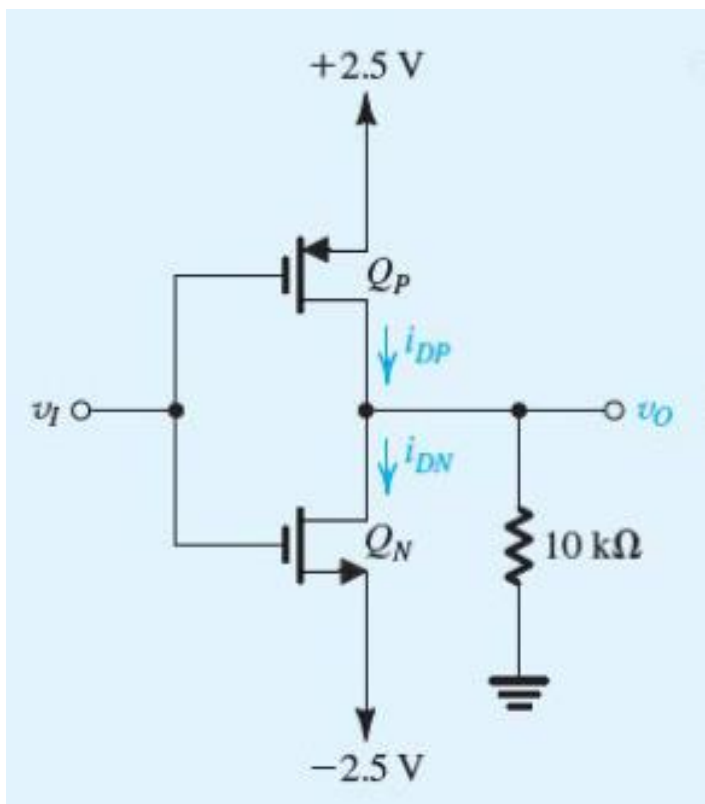
Circuit (b) _____



Example 5.8

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Assuming matched NMOS and PMOS transistors with $V_{thn} = -V_{thp} = 1V$, $K_n = K_p = 1mA/V^2$ and $\lambda = 0$, find the drain currents I_{Dn} and I_{Dp} , as well as the voltage v_o , for $v_i = 0V$, $+2.5V$, and $-2.5V$.



Last Lecture → MOS

- Two external voltage sources are required for biasing
- Three operation modes:

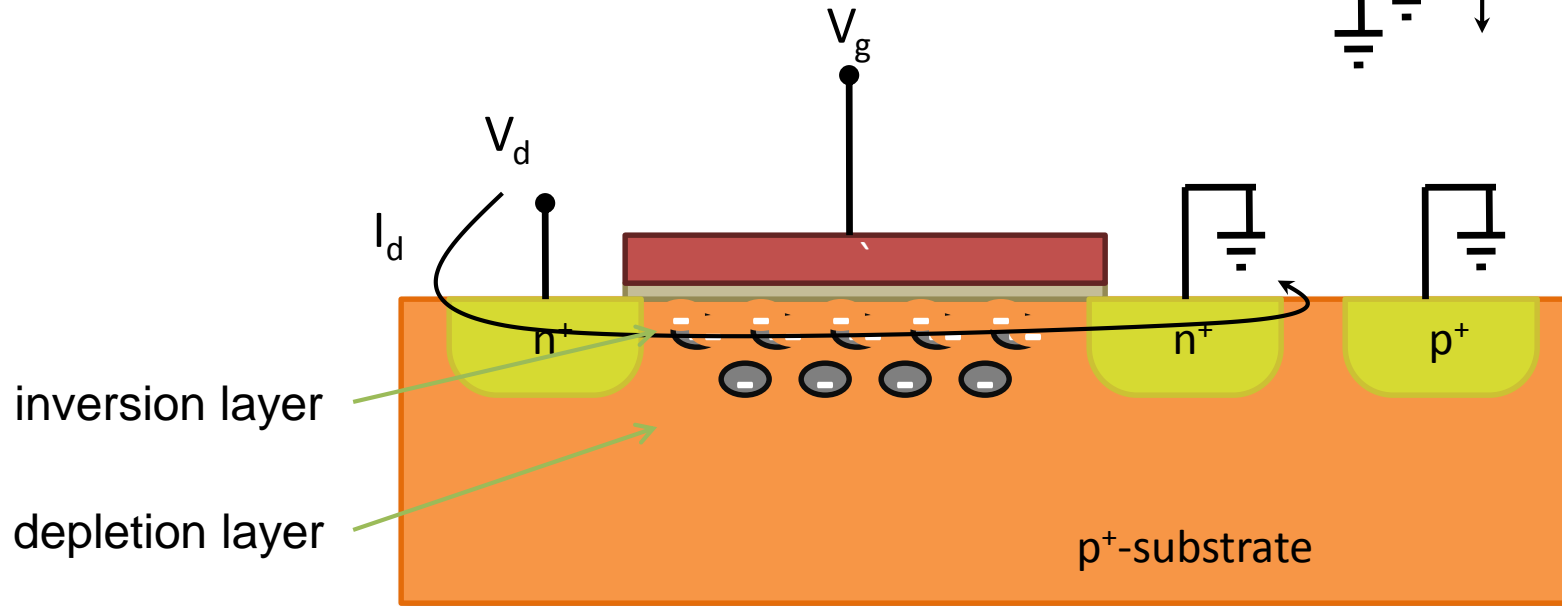
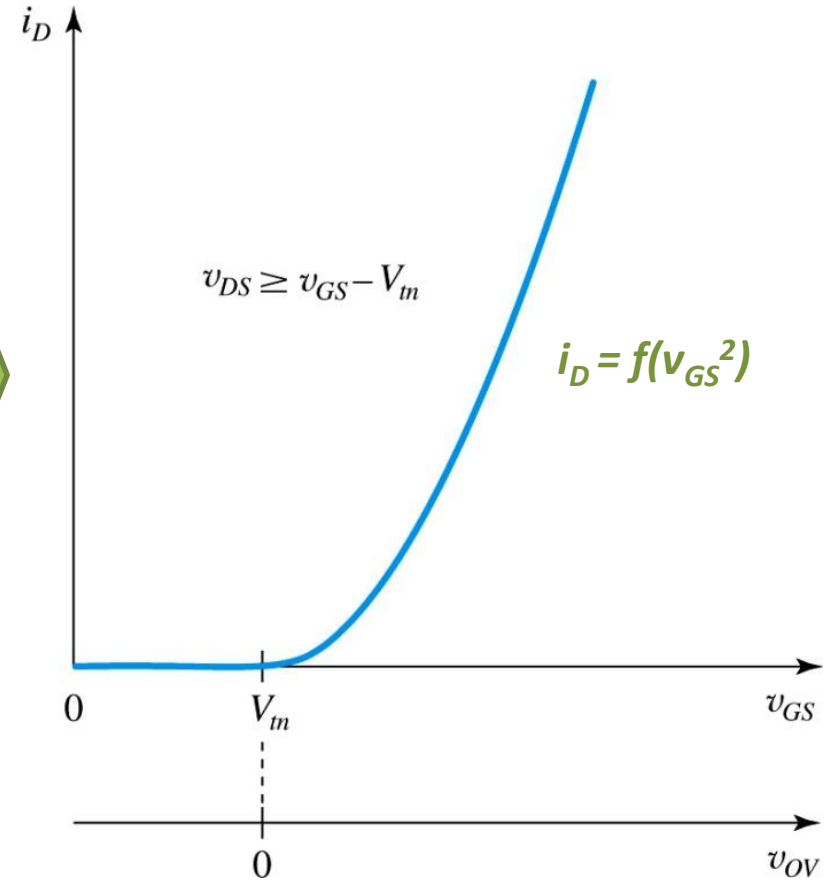
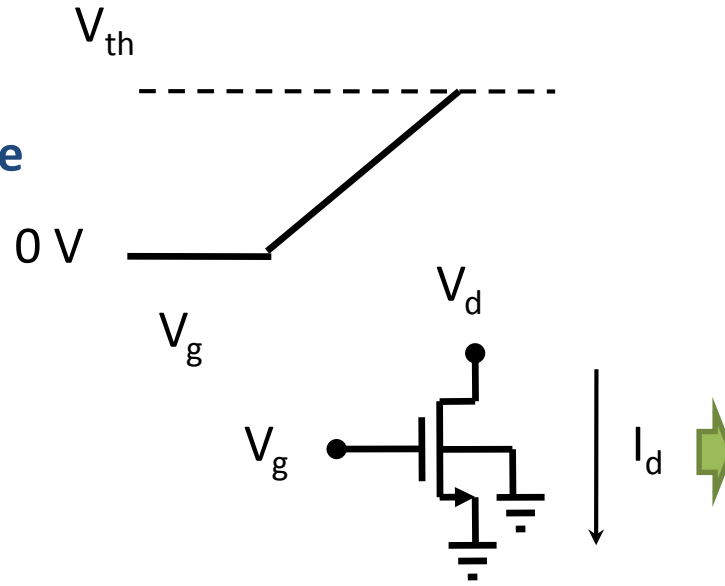
1) Cut-Off

used for switching!

2) Ohmic

3) Saturation

used for amplification!



Last Lecture → MOS DC Analysis

Triode

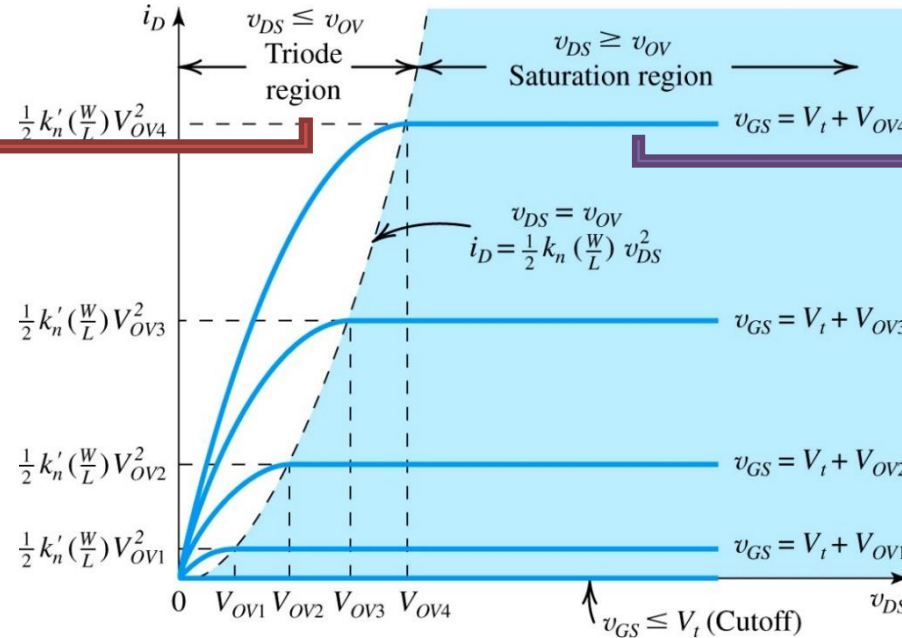
- $V_{GS} > V_{th}$
- $V_{DS} < V_{GS} - V_{th} = V_{ov}$
- $i_G = 0$

Transconductance Parameter [A/V²]

$$k_n' = \mu_n C_{ox}$$

$$I_D = k_n' \frac{W}{L} \left[(V_{GS} - V_{th})(V_{DS}) - \frac{1}{2} V_{DS}^2 \right]$$

$$\approx k_n' \frac{W}{L} (V_{GS} - V_{th}) \cdot V_{DS}$$



Saturation

- $V_{GS} > V_{th}$
- $V_{DS} > V_{GS} - V_{th} = V_{ov}$
- $i_G = 0$

Channel Length Modulation Parameter [1/V]

$$I_D = \frac{1}{2} K_n' \frac{W}{L} (V_{GS} - V_{th})^2 (1 + \lambda V_{DS})$$

$$\approx \frac{1}{2} k_n' \frac{W}{L} (V_{GS} - V_{th})^2$$

Exercise 5.5

An n-channel MOSFET operating with $V_{ov}=0.5V$ exhibits a linear resistance $r_{DS}=1k\Omega$ when v_{DS} is very small.

- ~~a) What is the value of the device trans-conductance parameter K_n ?~~
- ~~b) Assuming $\lambda = 0$, what is the value of the current I_D obtained when v_{DS} is increased to 0.5V? And to 1V?~~
- c) Assuming an $\lambda = 0.1V^{-1}$, what is the value of the current I_D obtained when v_{DS} is increased to 0.5V? And to 1V?